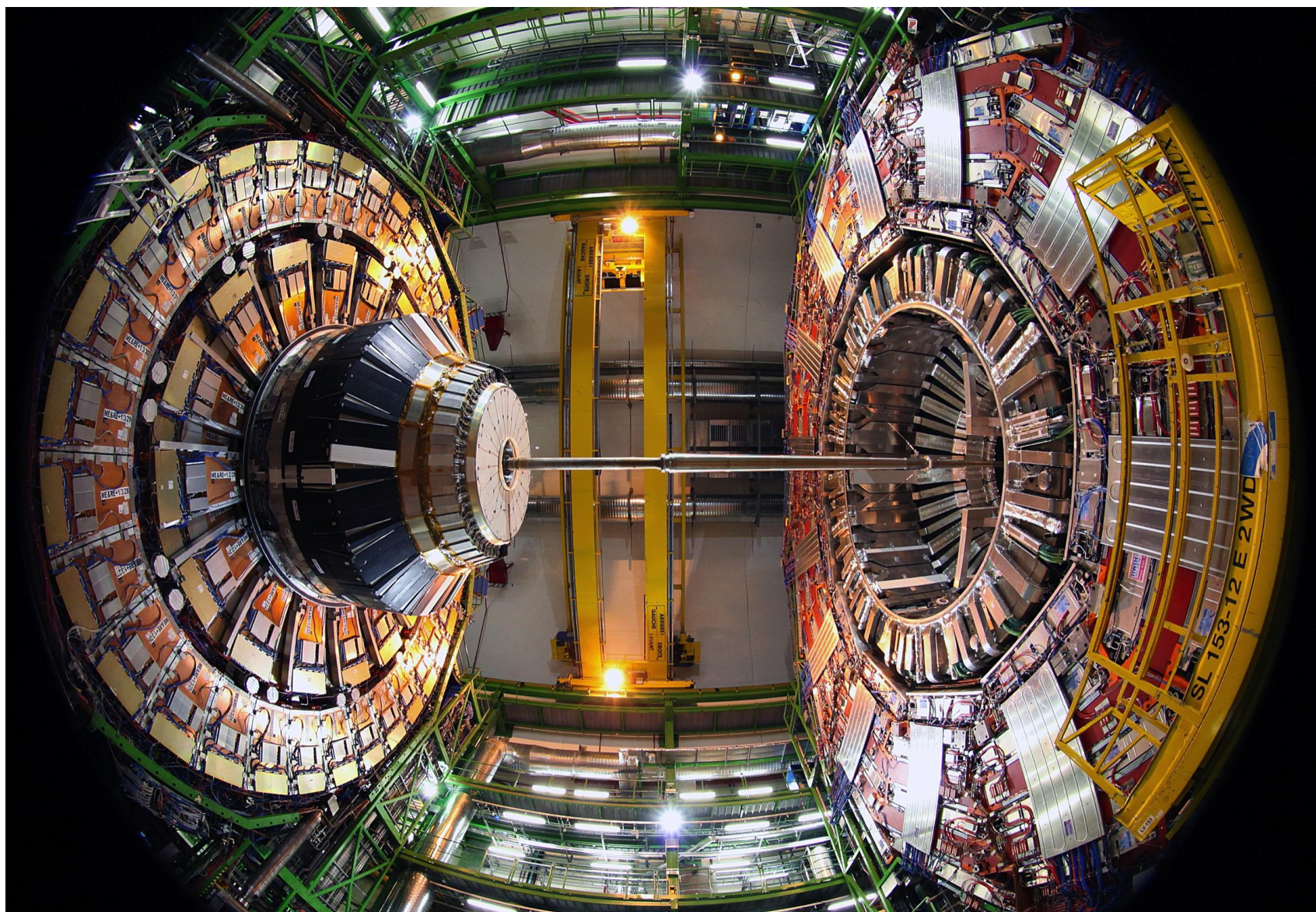
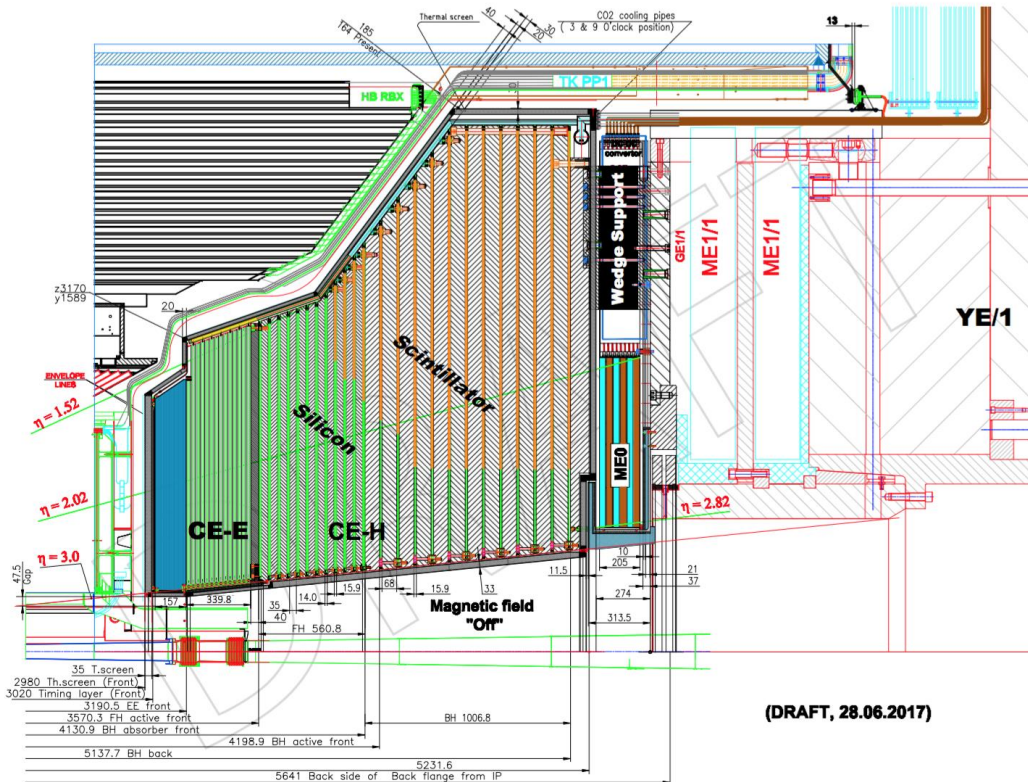




Phase II Endcap Calorimeter Upgrade: HGCAL



HGCAL Calorimeter Design: In Numbers



Construction:

- Hexagonal Si-sensors built into modules.
- **Modules** with a W/Cu backing plate and PCB readout board.
- Modules mounted on copper cooling plates to make wedge-shaped **cassettes**.
- **Cassettes** integrated into **absorber** structures

Key parameters:

- **600 m² of silicon**
- **6M ch, 0.5 or 1 cm² cell-size**
- **22000 modules (8" or 2x6" sensors)**
- **92,000 front-end ASICs.**
- **Power at end of life 120 kW.**

System Divided into three separate parts:

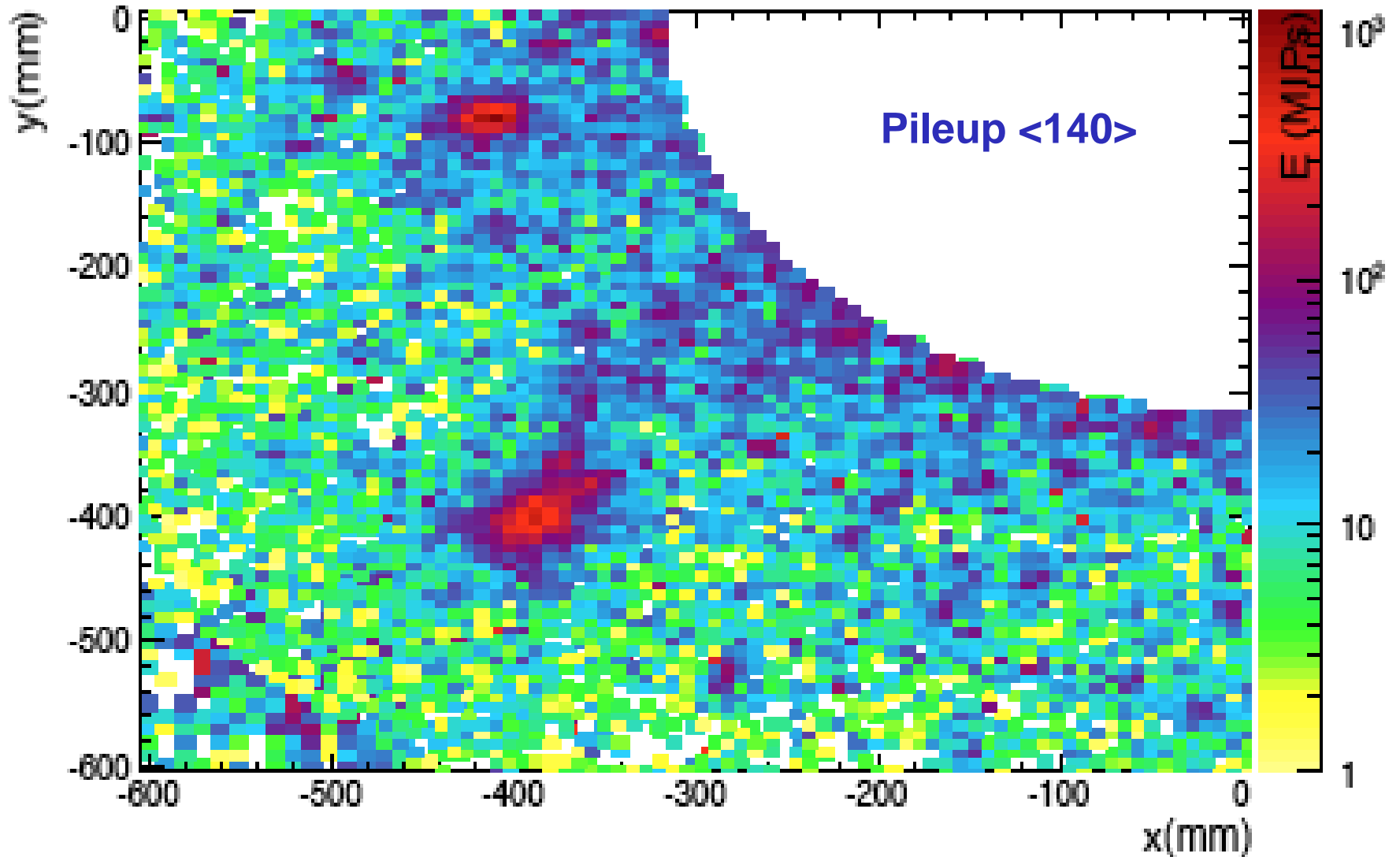
em calo (CE-E) – Silicon with tungsten/Pb absorber – 28 sampling layers – $25 X_0 + \sim 1.3 \lambda$

Hadronic (CE-H) – planes of Silicon OR silicon and scintillator tiles sandwiched between SS absorber plates – 24 sampling layers – 9λ

All the calorimeter is maintained at -30°C



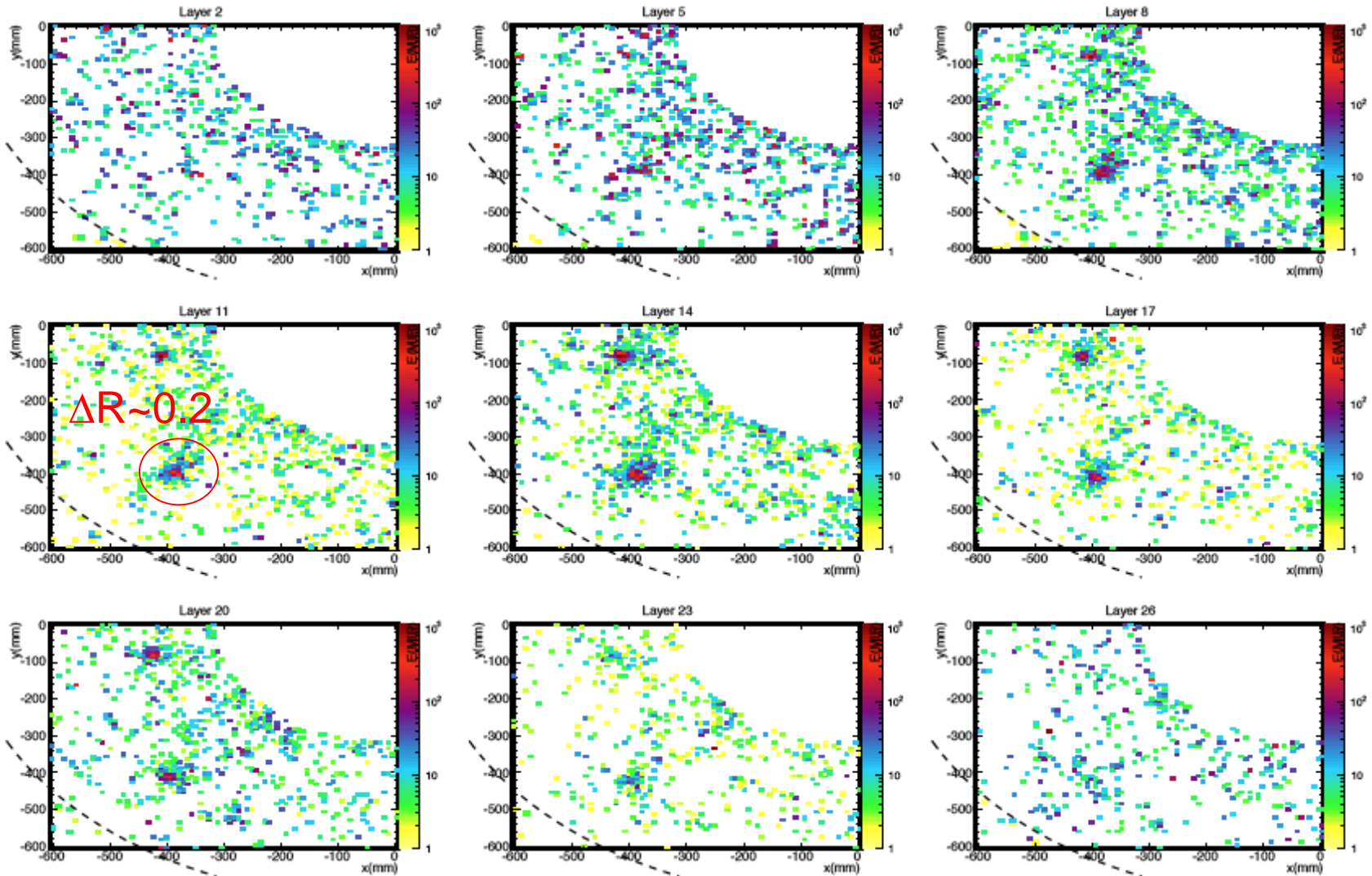
Event Display of VBF Jets ($VBF H \rightarrow \gamma\gamma$)





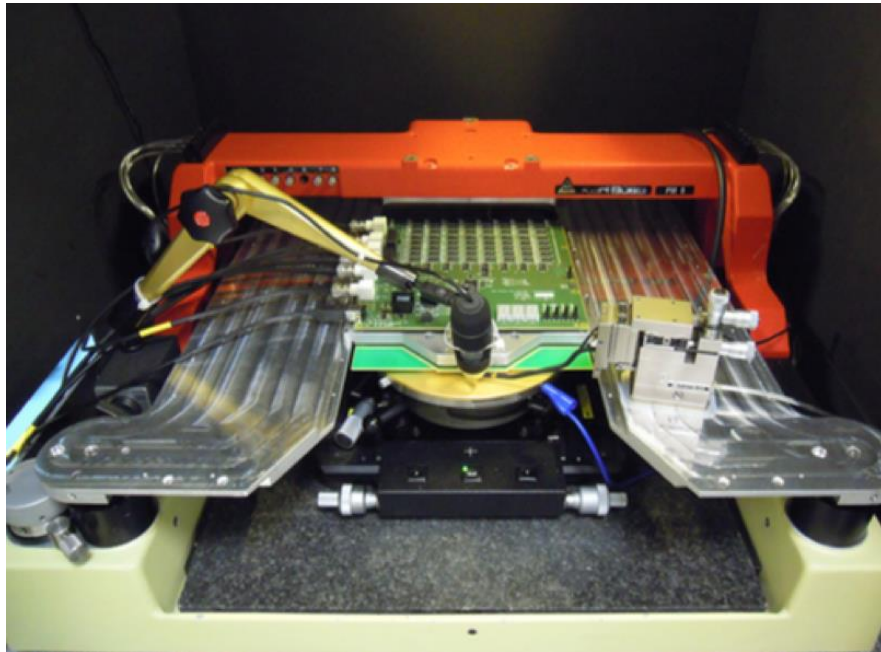
Event Display of VBF Jets ($VBF H \rightarrow \gamma\gamma$)

Standalone simulation: Taking Slices through ECAL section



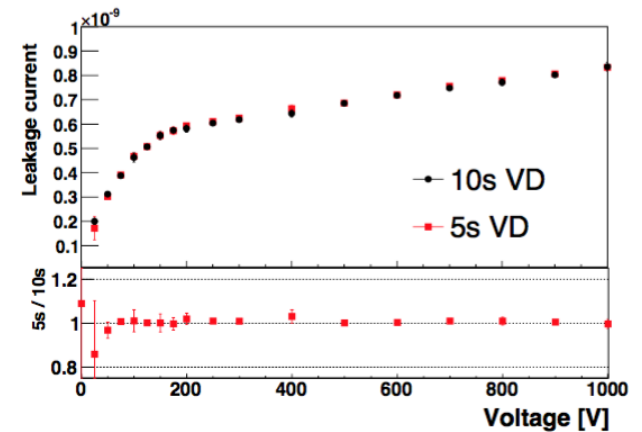


Example Of Si Sensors Testing Probe-card

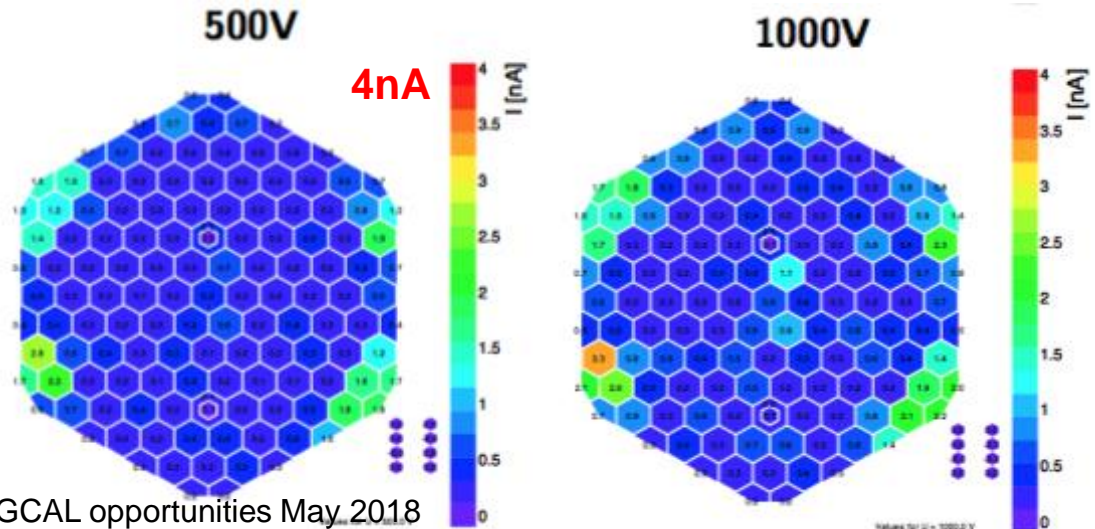


IV curve for one cell

- Connect cells with probe card and make single cell scans
- Identify stable measurement settings:
 - Time to wait after change of voltage (VD)

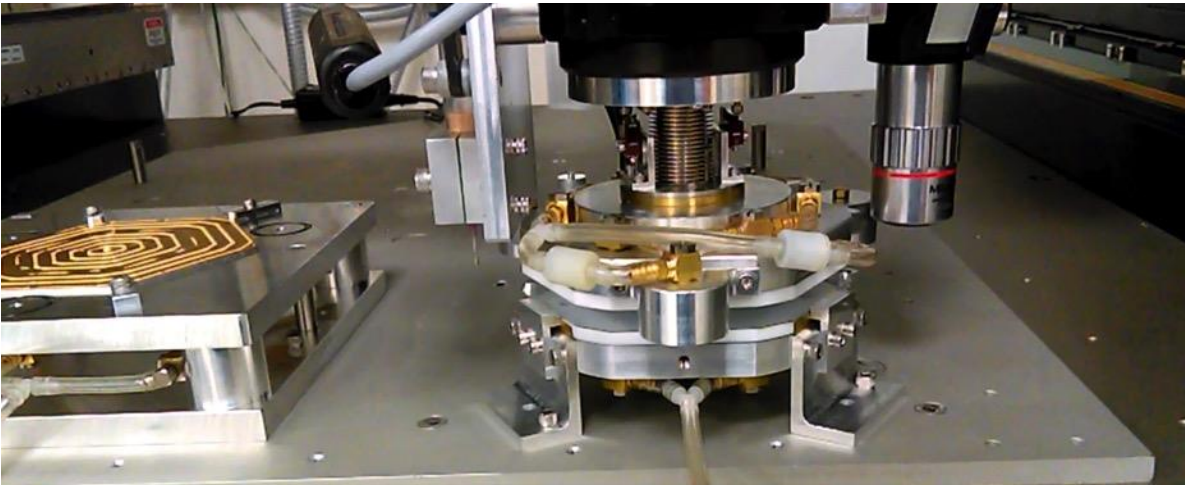
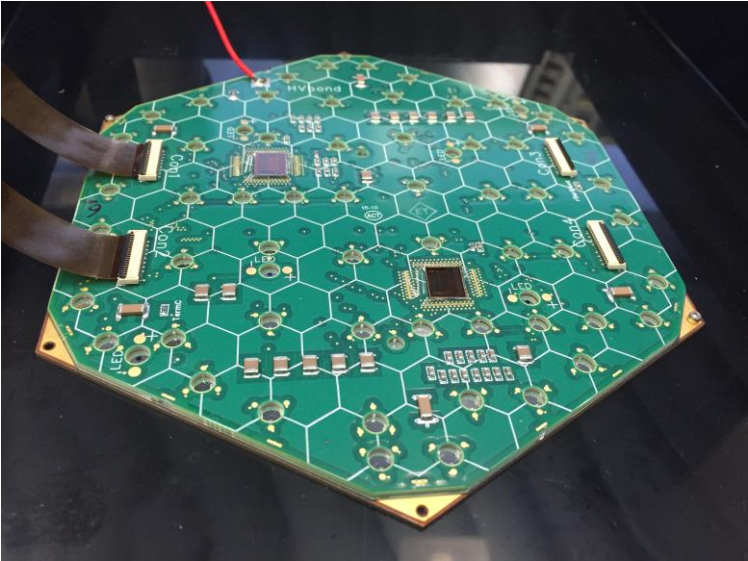


Whole wafer scans





Si Modules: Automated Assembly



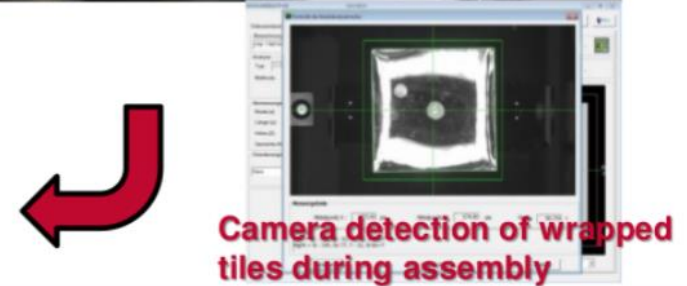
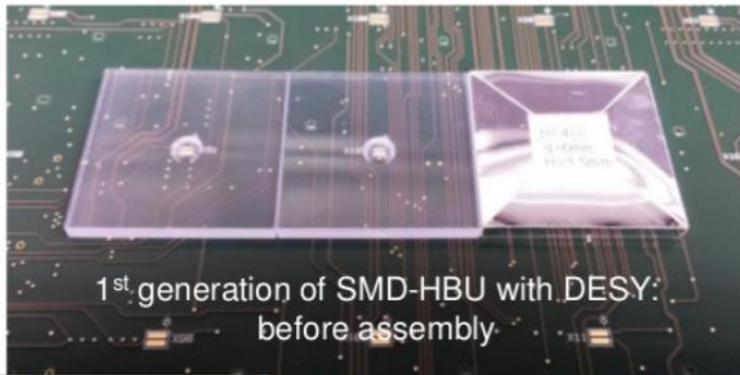
e.g. glue dispensed on aluminum baseplate with kapton



Wirebonder

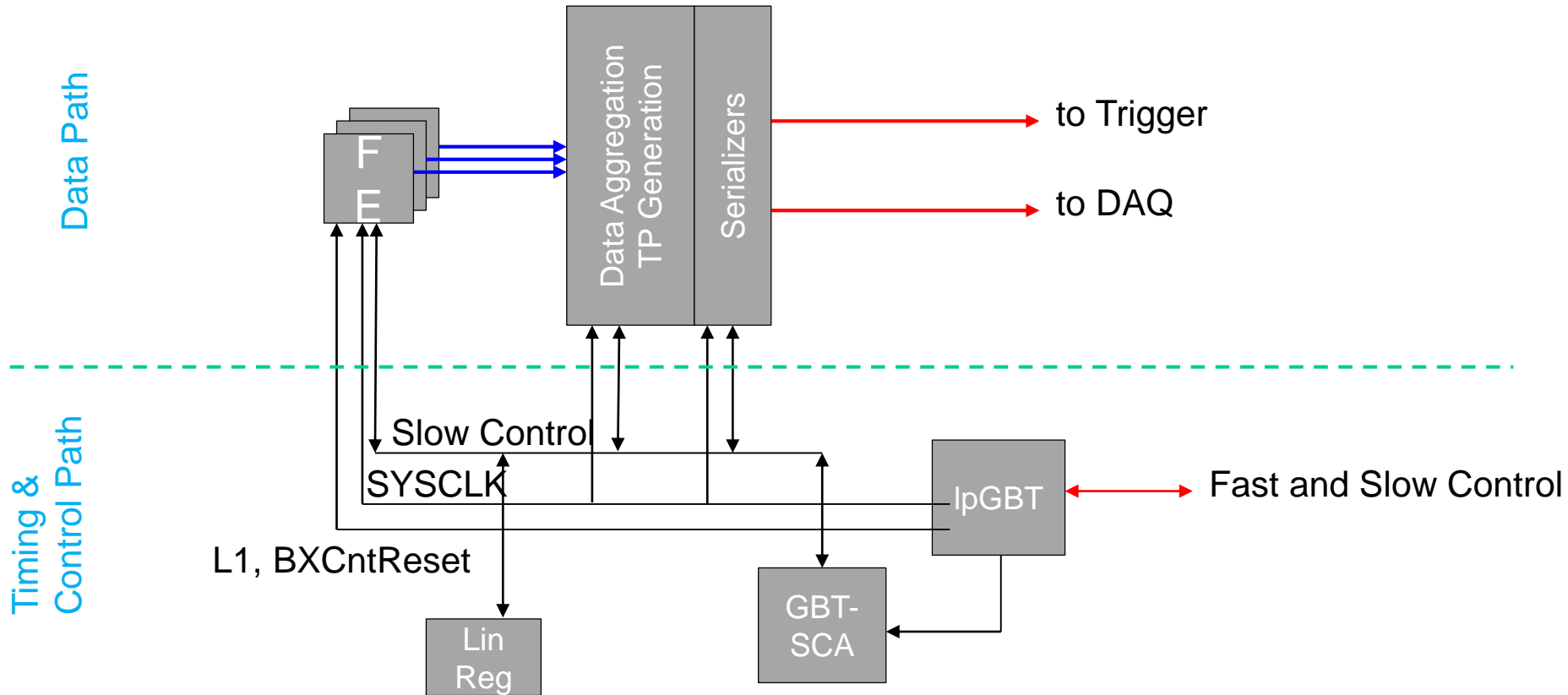


Plastic Scintillator Hadronic Part: SiPM-on-Tile Modules





HGCAL FE Readout Architecture

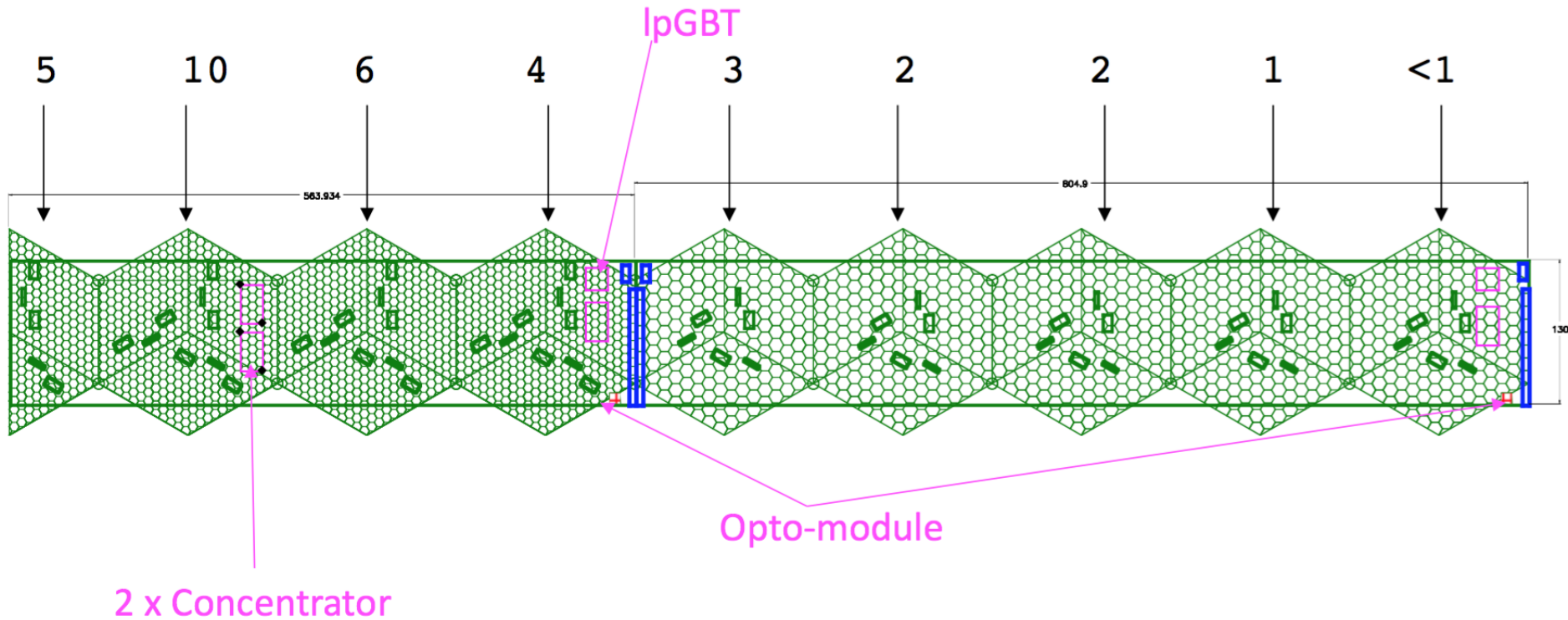




Sensors Boards and Motherboards

String of panels (2)

Rates (Gbit/sec):

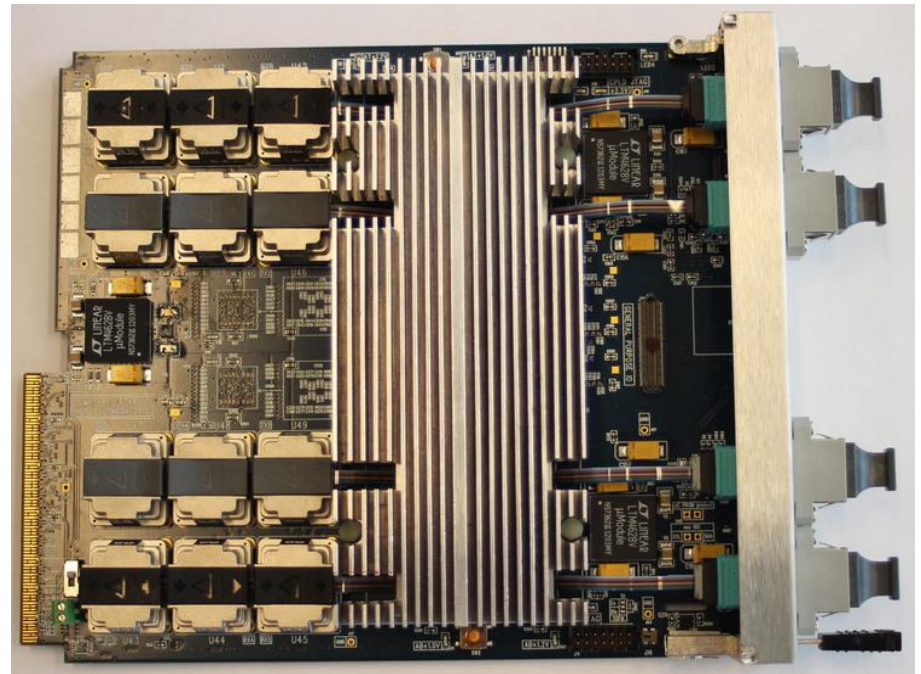
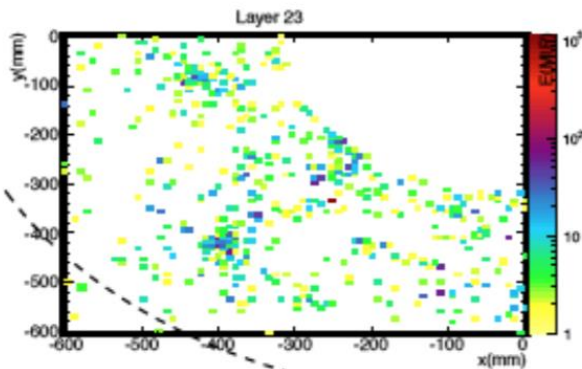
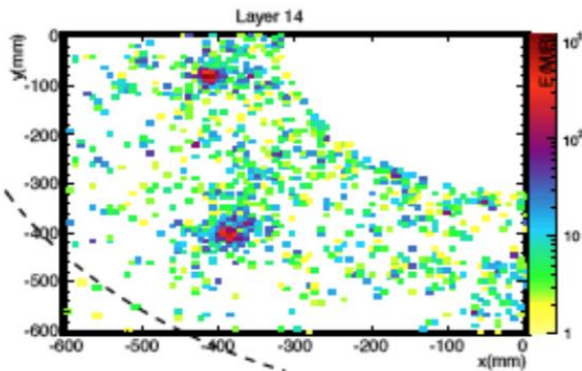
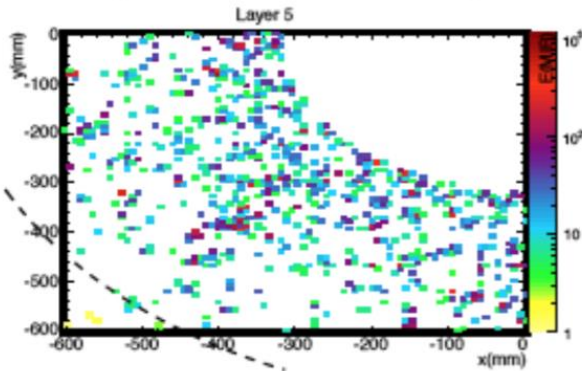




Trigger and Backend

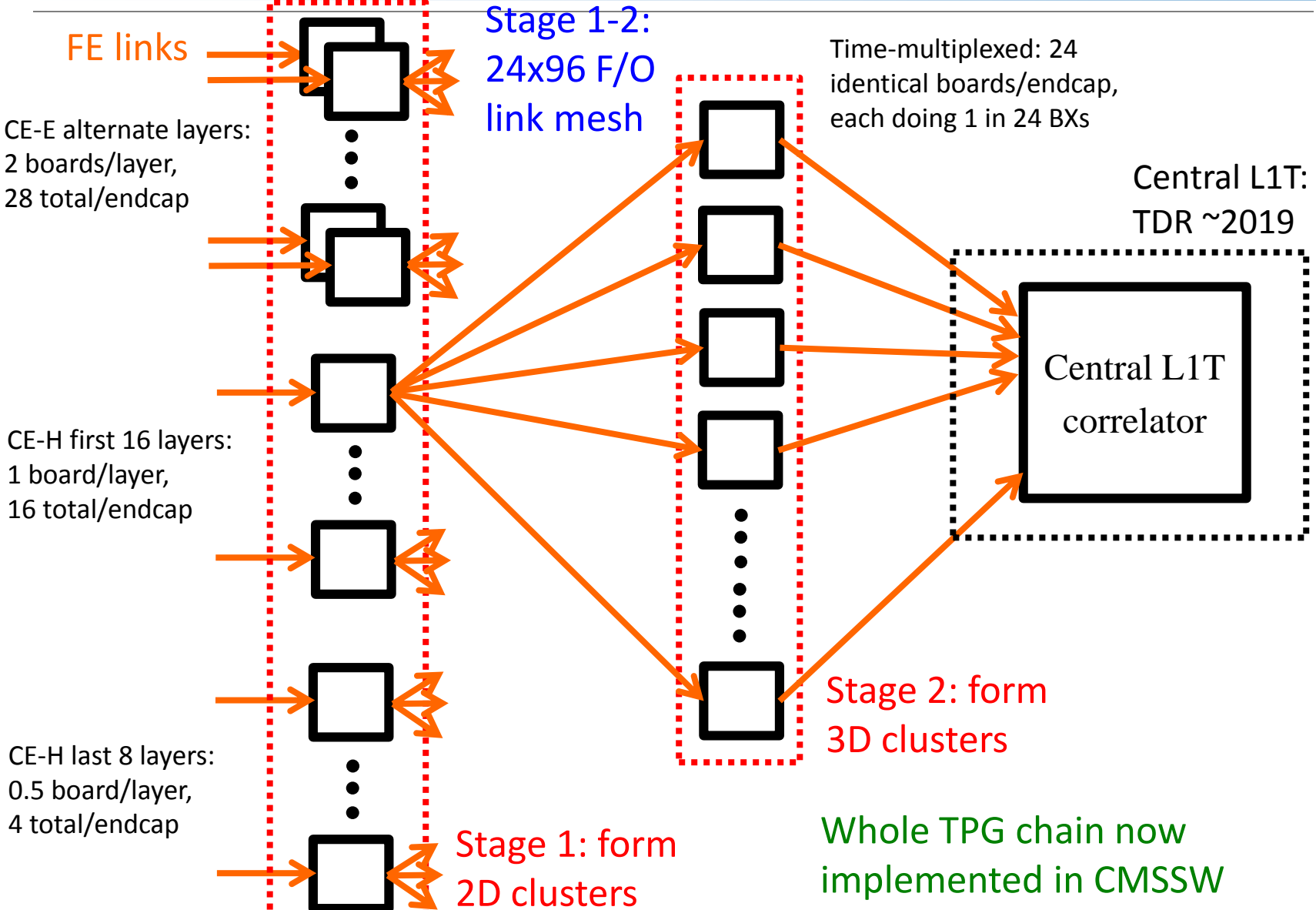
Particles seen in 3 planes (Layer 5, 14 and 23 out of 28 in the electromagnetic section)

A board in the current calorimeter trigger using an advanced FPGA





Overview of TDR architecture



Whole TPG chain now implemented in CMSSW



Summary - Possibilities

Mechanical Engineering

Participate in design, and manufacture

Electronics and Electrical Engineering

Design and testing, power systems (LV and HV)

Off-detector electronics

FPGA-based, design, firmware, software, machine learning,....

Active Elements (silicon sensors and SiPM-on-tile technology)

Testing and characterization – design and operate test benches

Module assembly and testing

Simulation, Reconstruction and Test Beam studies

Pattern recognition, machine leaning, ...

Ph.D. students, young postdocs etc.

Engineers, postdocs and students highly welcome to work with us at CERN



Physics Outlook: Questions for the LHC

1. SM contains too many apparently arbitrary features - *presumably these should become clearer as we make progress towards a unified theory.*

2. Clarify the e-w symmetry breaking sector

SM has an unproven element: the generation of mass
Higgs mechanism ->? or other physics ?

e.g. why $M_\gamma = 0$
 $M_W, M_Z \sim 100,000 \text{ MeV!}$

Answer will be found at **LHC energies**

***Transparency from
the early 90's***

3. SM gives nonsense at LHC energies

Probability of some processes becomes greater than 1 !! Nature's slap on the wrist!
Higgs mechanism provides a possible solution

4. Identify particles that make up Dark Matter

Even if the Higgs boson is found all is not completely well with SM alone:
next question is "Why is (Higgs) mass so low"?
If a new symmetry (Supersymmetry) is the answer, it must show up at $O(1\text{TeV})$

5. Search for new physics at the TeV scale

SM is logically incomplete – does not incorporate gravity

Superstring theory \Rightarrow dramatic concepts: supersymmetry , extra space-time dimensions ?



What makes it worthwhile to run longer an HEP experiment ?

1. Higher centre-of-mass energy
2. Higher integrated luminosity
3. Qualitatively better detectors